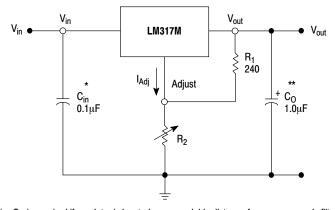
# Voltage Regulator - Adjustable Output, Positive 500 mA

The LM317M is an adjustable three-terminal positive voltage regulator capable of supplying in excess of 500 mA over an output voltage range of 1.2 V to 37 V. This voltage regulator is exceptionally easy to use and requires only two external resistors to set the output voltage. Further, it employs internal current limiting, thermal shutdown and safe area compensation, making it essentially blow-out proof.

The LM317M serves a wide variety of applications including local, on-card regulation. This device also makes an especially simple adjustable switching regulator, a programmable output regulator, or by connecting a fixed resistor between the adjustment and output, the LM317M can be used as a precision current regulator.

#### **Features**

- Output Current in Excess of 500 mA
- Output Adjustable between 1.2 V and 37 V
- Internal Thermal Overload Protection
- Internal Short Circuit Current Limiting
- Output Transistor Safe-Area Compensation
- Floating Operation for High Voltage Applications
- Eliminates Stocking Many Fixed Voltages
- NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These are Pb-Free Devices



 $\star$  =  $C_{in}$  is required if regulator is located an appreciable distance from power supply filter.

\*\* = 
$$C_0$$
 is not needed for stability, however, it does improve transient response.

$$V_{out} = 1.25 V \left( 1 + \frac{R_2}{R_1} \right) + I_{Adj} R_2$$

Since  $I_{Adj}$  is controlled to less than 100  $\mu$ A, the error associated with this term is negligible in most applications.

Figure 1. Simplified Application

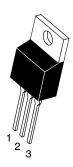


#### ON Semiconductor®

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Heatsink surface connected to Pin 2

TO-220AB T SUFFIX CASE 221AB



SOT-223 ST SUFFIX CASE 318E



DPAK DT SUFFIX CASE 369C



Heatsink Surface (shown as terminal 4 in case outline drawing) is connected to Pin 2.

PIN ASSIGNMENT		
1	Adjust	
2	$V_{\text{out}}$	
3	$V_{in}$	

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 11 of this data sheet.

#### **MAXIMUM RATINGS** (T<sub>A</sub> = 25°C, unless otherwise noted.)

Rating	Symbol	Value	Unit
Input-Output Voltage Differential	V <sub>I</sub> –V <sub>O</sub>	40	Vdc
Power Dissipation (Package Limitation) (Note 1)			
Plastic Package, T Suffix, Case 221A			
T <sub>A</sub> = 25°C	$P_{D}$	Internally Limited	
Thermal Resistance, Junction-to-Air	$\theta_{\sf JA}$	70	°C/W
Thermal Resistance, Junction-to-Case	$\theta_{\sf JC}$	5.0	°C/W
Plastic Package, DT Suffix, Case 369C			
T <sub>A</sub> = 25°C	$P_{D}$	Internally Limited	
Thermal Resistance, Junction-to-Air	$\theta_{\sf JA}$	92	°C/W
Thermal Resistance, Junction-to-Case	$\theta_{\sf JC}$	5.0	°C/W
Plastic Package, ST Suffix, Case 318E			
$T_A = 25^{\circ}C$	$P_{D}$	Internally Limited	
Thermal Resistance, Junction-to-Air	$\theta_{\sf JA}$	245	°C/W
Thermal Resistance, Junction-to-Case	$\theta_{\sf JC}$	15	°C/W
Maximum Junction Temperature	$T_{JMAX}$	+150	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **ELECTRICAL CHARACTERISTICS** ( $V_I - V_O = 5.0 \text{ V}$ ; $I_O = 0.1 \text{ A}$ , $T_J = T_{low}$ to $T_{high}$ (Note 2), unless otherwise noted.)

			LM317M/	LM317MB/NO	CV317MB	
Characteristics	Figure	Symbol	Min	Тур	Max	Unit
Line Regulation (Note 3) ( $T_A = 25^{\circ}C$ , 3.0 V $\leq$ V <sub>I</sub> $-$ V <sub>O</sub> $\leq$ 40 V)	3	Reg <sub>line</sub>	-	0.01	0.04	%/V
Load Regulation (Note 3)	4	Reg <sub>load</sub>				
$T_A = 25^{\circ}\text{C}$ , 10 mA $\leq I_O \leq 0.5 \text{ A}$ $V_O \leq 5.0 \text{ V}$			-	5.0	25	mV
$V_0 \ge 5.0 \text{ V}$			_	0.1	0.5	% V <sub>O</sub>
Adjustment Pin Current	5	$I_{Adj}$	-	50	100	μΑ
Adjustment Pin Current Change $2.5~V \le V_I - V_O \le 40~V,~10~mA \le I_L \le 0.5~A,~P_D \le P_{max}$	3, 4	$\Delta I_{Adj}$	-	0.2	5.0	μΑ
Reference Voltage 3.0 V $\leq$ V <sub>I</sub> $-$ V <sub>O</sub> $\leq$ 40 V, 10 mA $\leq$ I <sub>L</sub> $\leq$ 0.5 A, P <sub>D</sub> $\leq$ P <sub>max</sub>	5	V <sub>ref</sub>	1.20	1.25	1.30	V
Line Regulation 3.0 V ≤ V <sub>I</sub> –V <sub>O</sub> ≤ 40 V (Note 3)	3	Reg <sub>line</sub>	=	0.02	0.07	%/V
Load Regulation 10 mA $\leq$ I <sub>O</sub> $\leq$ 0.5 A (Note 3)	4	Reg <sub>load</sub>		00	70	mV
$V_0 \le 5.0 \text{ V}$ $V_0 \ge 5.0 \text{ V}$			-	20 0.3	70 1.5	% V <sub>O</sub>
Temperature Stability $(T_{low} \le T_J \le T_{high})$	5	T <sub>S</sub>	-	0.7	-	% V <sub>O</sub>
Minimum Load Current to Maintain Regulation (V <sub>I</sub> - V <sub>O</sub> = 40 V)	5	I <sub>Lmin</sub>	-	3.5	10	mA
$\begin{aligned} &\text{Maximum Output Current} \\ &V_I - V_O \leq 15 \text{ V, } P_D \leq P_{max} \\ &V_I - V_O = 40 \text{ V, } P_D \leq P_{max}, T_A = 25^{\circ}C \end{aligned}$	5	I <sub>max</sub>	0.5 0.15	0.9 0.25	- -	A
RMS Noise, % of $V_O$ ( $T_A = 25^{\circ}C$ , 10 Hz $\leq f \leq$ 10 kHz)	-	N	=	0.003	=	% V <sub>O</sub>
Ripple Rejection, $V_O$ = 10 V, f = 120 Hz (Note 4) Without $C_{Adj}$ $C_{Adj}$ = 10 $\mu F$	6	RR	- 66	65 80	- -	dB
Thermal Shutdown (Note 5)		_	_	180	_	°C
Long-Term Stability, T <sub>J</sub> = T <sub>high</sub> (Note 6) T <sub>A</sub> = 25°C for End-point Measurements	5	S	-	0.3	1.0	%/1.0 kHrs.

<sup>1.</sup> Figure 25 provides thermal resistance versus PC board pad size.

T<sub>low</sub> to T<sub>high</sub> = 0° to +125°C for LM317M
 T<sub>low</sub> to T<sub>high</sub> = -40° to +125°C for LM317MB, NCV317MB.
 Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.

<sup>4.</sup> C<sub>Adj</sub>, when used, is connected between the adjustment pin and ground.

<sup>5.</sup> Thermal characteristics are not subject to production test.

<sup>6.</sup> Since Long-Term Stability cannot be measured on each device before shipment, this specification is an engineering estimate of average stability from lot-to-lot.

 $\textbf{ELECTRICAL CHARACTERISTICS} \ (V_I - V_O = 5.0 \ V; \ I_O = 0.1 \ A, \ T_J = T_{low} \ to \ T_{high} \ (Note \ 7), \ unless \ otherwise \ noted.)$ 

			LM317MA/	LM317MAB/N	CV317MAB	
Characteristics	Figure	Symbol	Min	Тур	Max	Unit
Line Regulation (Note 8) ( $T_A = 25^{\circ}C$ , 3.0 $V \le V_I - V_O \le 40 \text{ V}$ )	3	Reg <sub>line</sub>	-	0.01	0.04	%/V
Load Regulation (Note 8) $T_A = 25^{\circ}C, \ 10 \ mA \le I_O \le 0.5 \ A$ $V_O \le 5.0 \ V$ $V_O \ge 5.0 \ V$	4	Reg <sub>load</sub>	- -	5.0 0.1	25 0.5	mV % V <sub>O</sub>
Adjustment Pin Current	5	$I_{Adj}$	_	50	100	μΑ
Adjustment Pin Current Change $2.5~V \le V_I - V_O \le 40~V,~10~mA \le I_L \le 0.5~A,~P_D \le P_{max}$	3, 4	$\Delta I_{Adj}$	-	0.2	5.0	μΑ
Reference Voltage 3.0 V $\leq$ V <sub>I</sub> - V <sub>O</sub> $\leq$ 40 V, 10 mA $\leq$ I <sub>L</sub> $\leq$ 0.5 A, P <sub>D</sub> $\leq$ P <sub>max</sub>	5	V <sub>ref</sub>	1.225	1.250	1.275	V
Line Regulation (Note 8) 3.0 V $\leq$ V <sub>I</sub> -V <sub>O</sub> $\leq$ 40 V	3	Reg <sub>line</sub>	-	0.02	0.07	%/V
Load Regulation (Note 8) 10 mA $\leq$ I $_{O} \leq$ 0.5 A $V_{O} \leq$ 5.0 V $V_{O} \geq$ 5.0 V	4	Reg <sub>load</sub>	- -	20 0.3	70 1.5	mV % V <sub>O</sub>
Temperature Stability $(T_{low} \le T_J \le T_{high})$	5	T <sub>S</sub>	-	0.7	-	% V <sub>O</sub>
Minimum Load Current to Maintain Regulation (V <sub>I</sub> – V <sub>O</sub> = 40 V)	5	I <sub>Lmin</sub>	-	3.5	10	mA
Maximum Output Current $V_I - V_O \le 15 \text{ V}, P_D \le P_{max}$ $V_I - V_O = 40 \text{ V}, P_D \le P_{max}, T_A = 25^{\circ}\text{C}$	5	I <sub>max</sub>	0.5 0.15	0.9 0.25	- -	А
RMS Noise, % of $V_O$ ( $T_A = 25^{\circ}C$ , 10 Hz $\leq$ f $\leq$ 10 kHz)	-	N	_	-	-	% Vo
Ripple Rejection, $V_O$ = 10 V, f = 120 Hz (Note 9) Without $C_{Adj}$ $C_{Adj}$ = 10 $\mu F$	6	RR	- 66	65 80	- -	dB
Thermal Shutdown (Note 10)	_	-	_	180	_	°C
Long-Term Stability, $T_J = T_{high}$ (Note 11) $T_A = 25^{\circ}C$ for End-point Measurements	5	S	-	0.3	1.0	%/1.0 kHrs.

T<sub>low</sub> to T<sub>high</sub> = 0° to +125°C for LM317MA T<sub>low</sub> to T<sub>high</sub> = -40° to +125°C for LM317MAB, NCV317MAB.
 Load and line regulation are specified at constant junction temperature. Changes in V<sub>O</sub> due to heating effects must be taken into account separately. Pulse testing with low duty cycle is used.
 C<sub>Adj</sub>, when used, is connected between the adjustment pin and ground.
 Thermal characteristics are not subject to production test.

<sup>11.</sup> Since Long-Term Stability cannot be measured on each device before shipment, this specification is an engineering estimate of average stability from lot-to-lot.

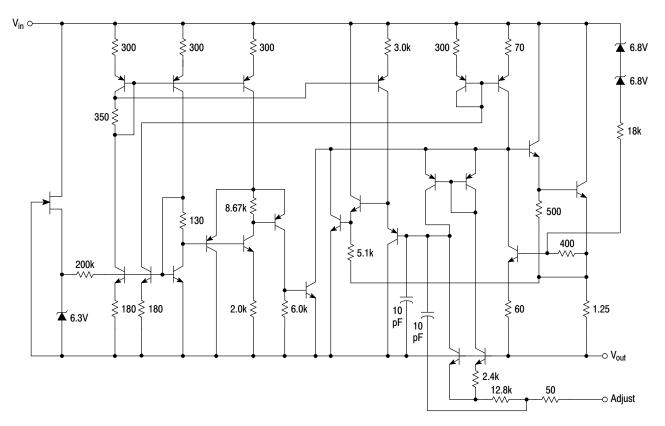


Figure 2. Representative Schematic Diagram

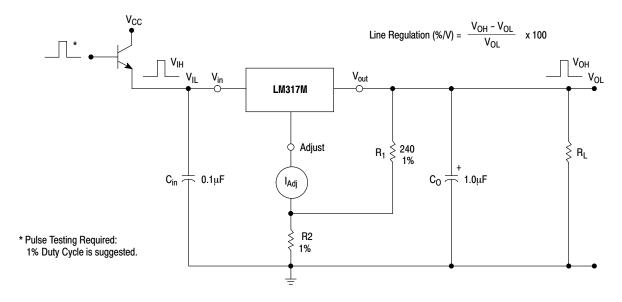
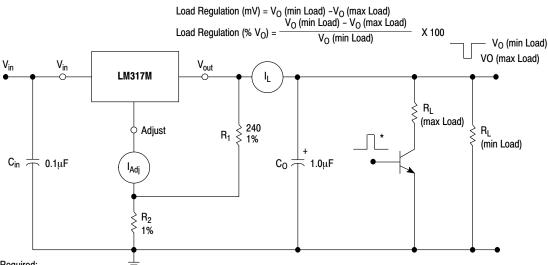


Figure 3. Line Regulation and  $\Delta I_{\mbox{\scriptsize Adj}}/\mbox{\scriptsize Line}$  Test Circuit



\* Pulse Testing Required: 1% Duty Cycle is suggested.

Figure 4. Load Regulation and  $\Delta I_{\mbox{Adj}}/\mbox{Load Test Circuit}$ 

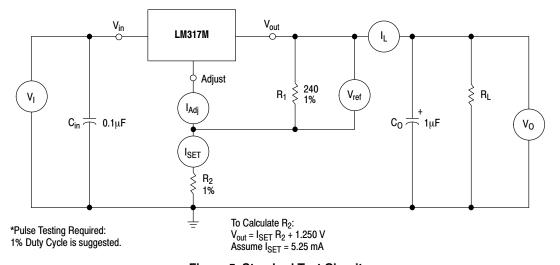


Figure 5. Standard Test Circuit

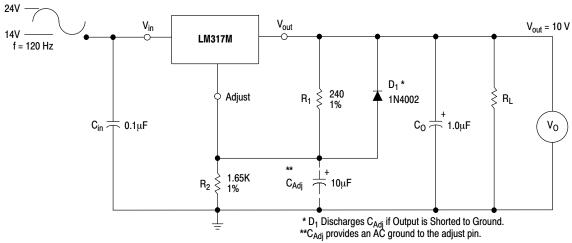


Figure 6. Ripple Rejection Test Circuit

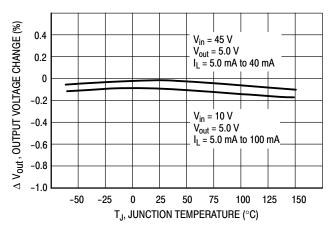


Figure 7. Load Regulation

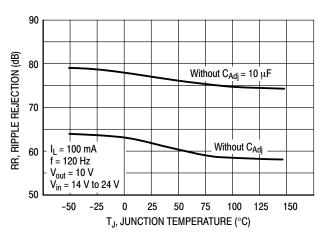


Figure 8. Ripple Rejection

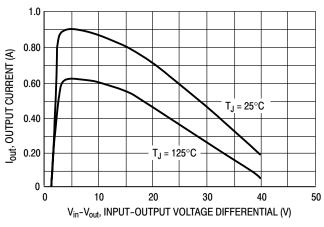


Figure 9. Current Limit

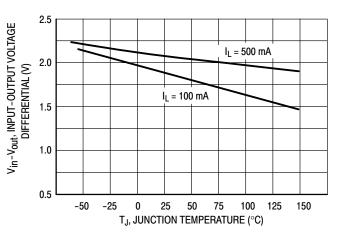
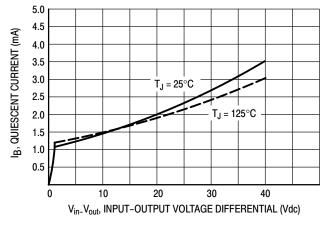


Figure 10. Dropout Voltage



**Figure 11. Minimum Operating Current** 

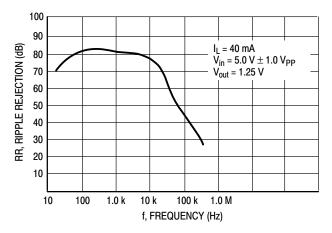


Figure 12. Ripple Rejection versus Frequency

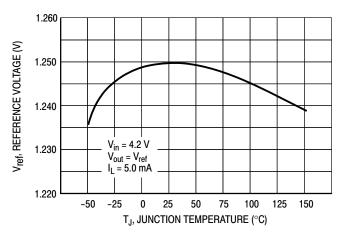


Figure 13. Temperature Stability

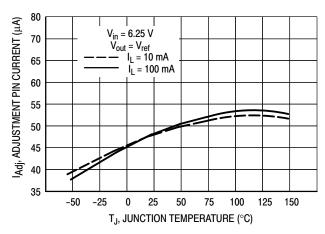


Figure 14. Adjustment Pin Current

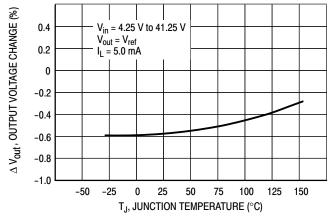


Figure 15. Line Regulation

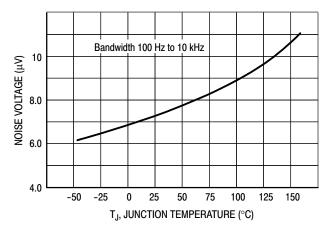


Figure 16. Output Noise

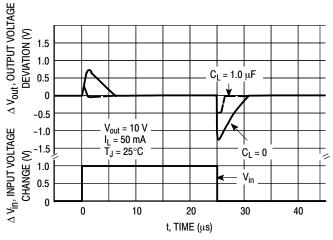


Figure 17. Line Transient Response

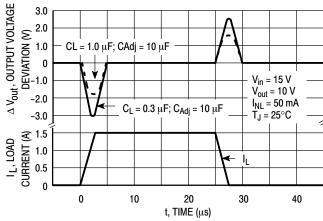


Figure 18. Load Transient Response

#### **APPLICATIONS INFORMATION**

#### **Basic Circuit Operation**

The LM317M is a three–terminal floating regulator. In operation, the LM317M develops and maintains a nominal 1.25 V reference ( $V_{ref}$ ) between its output and adjustment terminals. This reference voltage is converted to a programming current ( $I_{PROG}$ ) by  $R_1$  (see Figure 19), and this constant current flows through  $R_2$  to ground. The regulated output voltage is given by:

$$V_{out} = V_{ref} \left( 1 + \frac{R_2}{R_1} \right) + I_{Adj} R_2$$

Since the current from the terminal  $(I_{Adj})$  represents an error term in the equation, the LM317M was designed to control  $I_{Adj}$  to less than 100  $\mu A$  and keep it constant. To do this, all quiescent operating current is returned to the output terminal. This imposes the requirement for a minimum load current. If the load current is less than this minimum, the output voltage will rise.

Since the LM317M is a floating regulator, it is only the voltage differential across the circuit which is important to performance, and operation at high voltages with respect to ground is possible.

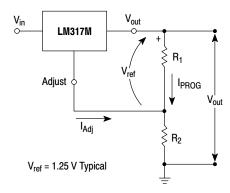


Figure 19. Basic Circuit Configuration

#### **Load Regulation**

The LM317M is capable of providing extremely good load regulation, but a few precautions are needed to obtain maximum performance. For best performance, the programming resistor  $(R_1)$  should be connected as close to the regulator as possible to minimize line drops which effectively appear in series with the reference, thereby degrading regulation. The ground end of  $R_2$  can be returned near the load ground to provide remote ground sensing and improve load regulation.

#### **External Capacitors**

A  $0.1\,\mu F$  disc or  $1.0\,\mu F$  tantalum input bypass capacitor ( $C_{in}$ ) is recommended to reduce the sensitivity to input line impedance.

The adjustment terminal may be bypassed to ground to improve ripple rejection. This capacitor ( $C_{Adj}$ ) prevents ripple from being amplified as the output voltage is increased. A 10  $\mu F$  capacitor should improve ripple rejection about 15 dB at 120 Hz in a 10 V application.

Although the LM317M is stable with no output capacitance, like any feedback circuit, certain values of external capacitance can cause excessive ringing. An output capacitance ( $C_O$ ) in the form of a 1.0  $\mu F$  tantalum or 25  $\mu F$  aluminum electrolytic capacitor on the output swamps this effect and insures stability.

#### **Protection Diodes**

When external capacitors are used with any IC regulator it is sometimes necessary to add protection diodes to prevent the capacitors from discharging through low current points into the regulator.

Figure 20 shows the LM317M with the recommended protection diodes for output voltages in excess of 25 V or high capacitance values ( $C_O > 25~\mu F$ ,  $C_{Adj} > 5.0~\mu F$ ). Diode  $D_1$  prevents  $C_O$  from discharging thru the IC during an input short circuit. Diode  $D_2$  protects against capacitor  $C_{Adj}$  discharging through the IC during an output short circuit. The combination of diodes  $D_1$  and  $D_2$  prevents  $C_{Adj}$  from discharging through the IC during an input short circuit.

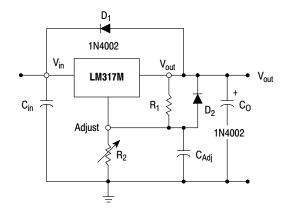


Figure 20. Voltage Regulator with Protection Diodes

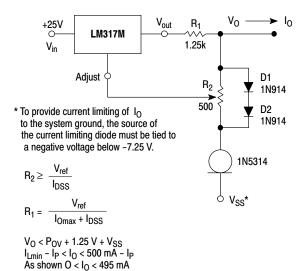
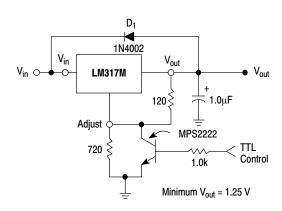


Figure 21. Adjustable Current Limiter



D<sub>1</sub> protects the device during an input short circuit.

Figure 22. 5 V Electronic Shutdown Regulator

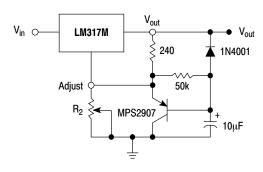


Figure 23. Slow Turn-On Regulator

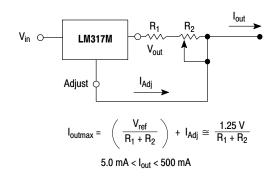


Figure 24. Current Regulator

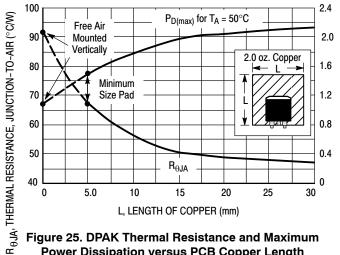


Figure 25. DPAK Thermal Resistance and Maximum Power Dissipation versus PCB Copper Length

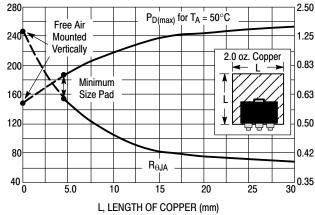


Figure 26. SOT-223 Thermal Resistance and Maximum **Power Dissipation versus PCB Copper Length** 

#### **ORDERING INFORMATION**

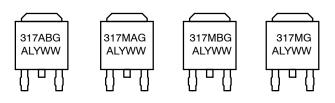
Device	Output Voltage Tolerance	Operating Temperature Range	Package	Shipping <sup>†</sup>
LM317MABDTG			DPAK (Pb-Free)	75 Units / Rail
LM317MABDTRKG			DPAK	2500 / Tape & Reel
NCV317MABDTRKG*		T <sub>.1</sub> = -40°C to 125°C	(Pb-Free)	
NCV317MABSTT3G*	2%	1,1 40 0 10 120 0	SOT-223 (Pb-Free)	4000 / Tape & Reel
LM317MABTG			TO-220 (Pb-Free)	50 Units / Rail
LM317MADTRKG		T <sub>J</sub> = 0°C to 125°C	DPAK (Pb-Free)	2500 / Tape & Reel
LM317MBDTG			DPAK	75 Units / Rail
NCV317MBDTG*		_	(Pb-Free)	
LM317MBDTRKG			DPAK	2500 / Tape & Reel
NCV317MBDTRKG*			(Pb-Free)	
LM317MBSTT3G		$T_J = -40^{\circ}\text{C to } 125^{\circ}\text{C}$	SOT-223	4000 / Tape & Reel
NCV317MBSTT3G*			(Pb-Free)	
LM317MBTG			TO-220	50 Units / Rail
NCV317MBTG*	4%		(Pb-Free)	
LM317MDTG			DPAK (Pb-Free)	75 Units / Rail
LM317MDTRKG		T 000 L 10500	DPAK (Pb-Free)	2500 / Tape & Reel
LM317MSTT3G		T <sub>J</sub> = 0°C to 125°C	SOT-223 (Pb-Free)	4000 / Tape & Reel
LM317MTG			TO-220 (Pb-Free)	50 Units / Rail

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

\*NCV devices: T<sub>low</sub> = -40°C, T<sub>high</sub> = +125°C. Guaranteed by design. NCV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

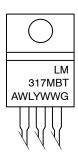
#### **MARKING DIAGRAMS**

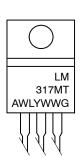
DPAK DT SUFFIX CASE 369C

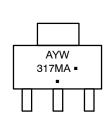


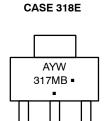
TO-220 T SUFFIX CASE 221A

LM 317MABT AWLYWWG



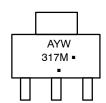






SOT-223

ST SUFFIX



A = Assembly Location

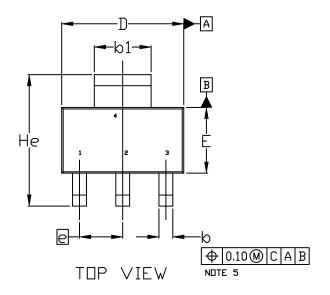
L, WL = Wafer Lot
Y = Year
WW, W = Work Week
G or = Pb-Free Package

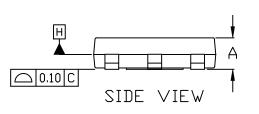
(Note: Microdot may be in either location)

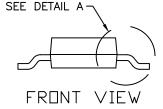


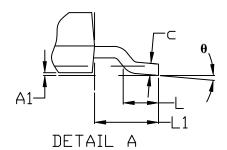
**SOT-223 (TO-261)** CASE 318E-04 ISSUE R

**DATE 02 OCT 2018** 





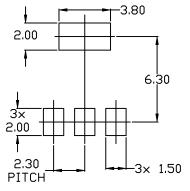




#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. DIMENSIONS D & E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.200MM PER SIDE.
- 4. DATUMS A AND B ARE DETERMINED AT DATUM H.
- 5. ALLIS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.
- 6. POSITIONAL TOLERANCE APPLIES TO DIMENSIONS 6 AND 61.

	MI	LLIMETE	RS
DIM	MIN.	N□M.	MAX.
Α	1.50	1.63	1.75
A1	0.02	0.06	0.10
b	0.60	0.75	0.89
b1	2.90	3.06	3.20
C	0.24	0.29	0.35
D	6.30	6.50	6.70
E	3.30	3.50	3.70
е		2,30 BSC	,
L	0.20		
L1	1.50	1.75	2.00
He	6.70	7.00	7.30
θ	0°		10°



RECOMMENDED MOUNTING FOOTPRINT

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DESCF	RIPTION:	SOT-223 (TO-261)		PAGE 1 OF 2

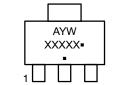
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#### SOT-223 (TO-261) CASE 318E-04 ISSUE R

**DATE 02 OCT 2018** 

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. ANODE 2. CATHODE 3. NC 4. CATHODE	STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 4: PIN 1. SOURCE 2. DRAIN 3. GATE 4. DRAIN	STYLE 5: PIN 1. DRAIN 2. GATE 3. SOURCE 4. GATE
STYLE 6: PIN 1. RETURN 2. INPUT 3. OUTPUT 4. INPUT	STYLE 7: PIN 1. ANODE 1 2. CATHODE 3. ANODE 2 4. CATHODE	STYLE 8: CANCELLED	STYLE 9: PIN 1. INPUT 2. GROUND 3. LOGIC 4. GROUND	STYLE 10: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE
STYLE 11: PIN 1. MT 1 2. MT 2 3. GATE 4. MT 2	STYLE 12: PIN 1. INPUT 2. OUTPUT 3. NC 4. OUTPUT	STYLE 13: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR		

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location Α

= Year

W = Work Week XXXXX = Specific Device Code

= Pb-Free Package

(Note: Microdot may be in either location) \*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "•", may or may be present. Some products may

not follow the Generic Marking.

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DESCRIPTION:	SOT-223 (TO-261)		PAGE 2 OF 2

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### **MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS** 





#### **TO-220, SINGLE GAUGE** CASE 221AB-01 **ISSUE A**

**DATE 16 NOV 2010** 

- NOTES:

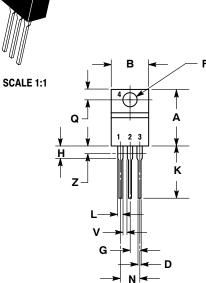
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

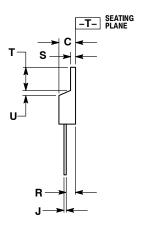
  2. CONTROLLING DIMENSION: INCHES.

  3. DIMENSION 2 DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARTIES ARE ALLOWED.

  4. PRODUCT SHIPPED PRIOR TO 2008 HAD DIMENSIONS S = 0.045 0.055 INCHES (1.143 1.397 MM)

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
U	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
7	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
œ	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.020	0.024	0.508	0.61
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04





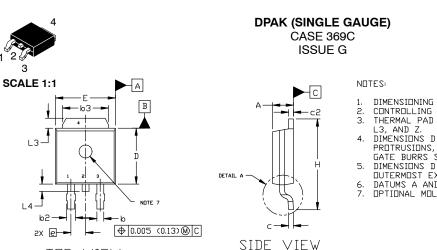
STYLE 1:		STYLE 2:		STYLE 3:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE
2.	COLLECTOR	2.	EMITTER	2.	ANODE
3.	EMITTER	3.	COLLECTOR	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE
STYLE 5:		STYLE 6:		STYLE 7:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE
4.	DRAIN	4.	CATHODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11:	
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN
2.	COLLECTOR	2.	SOURCE	2.	SOURCE
3.	EMITTER	3.	DRAIN	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE

 MAIN TERMINAL 1 MAIN TERMINAL 2 GATE MAIN TERMINAL 2
 CATHODE ANODE EXTERNAL TRIP/DELAY ANODE

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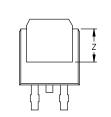
**DATE 31 MAY 2023** 

- DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCHES
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS 63,
- L3, AND Z.

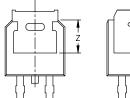
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH,
  PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR
  GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  DIMENSIONS D AND E ARE DETERMINED AT THE
  OUTERMOST EXTREMES OF THE PLASTIC BODY.
  DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
  DETININAL MOLD ESCALUPE.

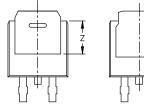
- OPTIONAL MOLD FEATURE.

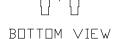
DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
C	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090 BSC		2.29 BSC	
Η	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	



TOP VIEW

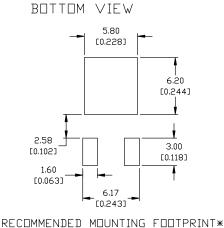




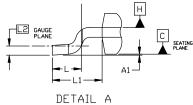


ALTERNATE

CONSTRUCTIONS

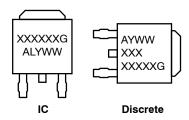


\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DUWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



CW ROTATED 90°

#### **GENERIC MARKING DIAGRAM\***



XXXXXX	= Device Code
Α	= Assembly Location
L	= Wafer Lot
Υ	= Year
WW	= Work Week
G	= Pb-Free Package

STYLE 1: PIN 1. BASE STYLE 2: PIN 1. GATE STYLE 3: PIN 1. ANODE STYLE 4: PIN 1. CATHODE STYLE 5: PIN 1. GATE 2. COLLECTOR 2. DRAIN 2. CATHODE 2. ANODE 2. ANODE 3 SOURCE 3 CATHODE 3 FMITTER 3 ANODE 3 GATE COLLECTOR 4. DRAIN CATHODE 4. ANODE ANODE

STYLE 6: STYLE 7: PIN 1. GATE 2. COLLECTOR STYLE 8: STYLE 9: STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE PIN 1. MT1 2. MT2 PIN 1. N/C 2. CATHODE 3. ANODE PIN 1. ANODE 2. CATHODE 3 FMITTER 3 RESISTOR ADJUST 3 GATE 4. COLLECTOR 4. CATHODE 4. ANODE CATHODE

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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